NPN Silicon Planar Epitaxial Transistor

PZT2222A

This NPN Silicon Epitaxial transistor is designed for use in linear and switching applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

Features

- PNP Complement is PZT2907AT1
- The SOT-223 Package Can be Soldered Using Wave or Reflow
- SOT-223 Package Ensures Level Mounting, Resulting in Improved Thermal Conduction, and Allows Visual Inspection of Soldered Joints
- The Formed Leads Absorb Thermal Stress During Soldering, Eliminating the Possibility of Damage to the Die
- Available in 12 mm Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CBO}	75	Vdc
Emitter-Base Voltage (Open Collector)	V _{EBO}	6.0	Vdc
Collector Current	Ι _C	600	mAdc
Total Power Dissipation up to T _A = 25°C (Note 1)	P _D	1.5	W
Storage Temperature Range	T _{stg}	– 65 to +150	°C
Junction Temperature Range	TJ	– 55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

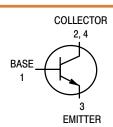
Device mounted on an epoxy printed circuit board 1.575 inches x 1.575 inches x 0.059 inches; mounting pad for the collector lead min. 0.93 inches².

THERMAL CHARACTERISTICS

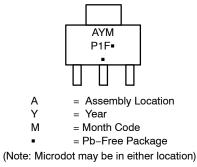
Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.3	°C/W
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	ΤL	260 10	°C Sec

SOT-223 PACKAGE NPN SILICON TRANSISTOR SURFACE MOUNT

SOT-223 (TO-261) CASE 318E-04 STYLE 1







ORDERING INFORMATION

Device	Package	Shipping [†]
PZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
SPZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
PZT2222AT3G	SOT-223 (Pb-Free)	4,000 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 10$ mAdc, I_E	₃ = 0)	V _{(BR)CEO}	40	-	Vdc
Collector-Base Breakdown Voltage (I_C = 10 µAdc, I_E =	0)	V _{(BR)CBO}	75	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = 10 \ \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	6.0	-	Vdc
Base-Emitter Cutoff Current ($V_{CE} = 60 \text{ Vdc}, V_{BE} = -3.$	0 Vdc)	I _{BEX}	-	20	nAdc
Collector-Emitter Cutoff Current (V_{CE} = 60 Vdc, V_{BE} =	– 3.0 Vdc)	I _{CEX}	-	10	nAdc
Emitter-Base Cutoff Current (V_{EB} = 3.0 Vdc, I_{C} = 0)		I _{EBO}	-	100	nAdc
Collector–Base Cutoff Current ($V_{CB} = 60$ Vdc, $I_E = 0$) ($V_{CB} = 60$ Vdc, $I_E = 0$, $T_A = 125^{\circ}C$)		I _{CBO}		10 10	nAdc μAdc
ON CHARACTERISTICS					
DC Current Gain (I _C = 0.1 mAdc, V _{CE} = 10 Vdc) (I _C = 1.0 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc, T _A = -55° C) (I _C = 150 mAdc, V _{CE} = 10 Vdc) (I _C = 150 mAdc, V _{CE} = 1.0 Vdc) (I _C = 500 mAdc, V _{CE} = 10 Vdc)		h _{FE}	35 50 70 35 100 50 40	- - - 300 - -	-
Collector-Emitter Saturation Voltages ($I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc}$) ($I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc}$)		V _{CE(sat)}		0.3 1.0	Vdc
Base-Emitter Saturation Voltages (I _C = 150 mAdc, I _B = 15 mAdc) (I _C = 500 mAdc, I _B = 50 mAdc)		V _{BE(sat)}	0.6 _	1.2 2.0	Vdc
Input Impedance (V_{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V_{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)		h _{ie}	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)		h _{re}		8.0x10 ⁻⁴ 4.0x10 ⁻⁴	_
Small–Signal Current Gain (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)		h _{fe}	50 75	300 375	_
Output Admittance (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)		h _{oe}	5.0 25	35 200	μmhos
Noise Figure (V _{CE} = 10 Vdc, I _C = 100 μ Adc, f = 1.0 kHz	z)	F	-	4.0	dB
DYNAMIC CHARACTERISTICS					
Current–Gain – Bandwidth Product (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)		f _T	300	-	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)		C _c	-	8.0	pF
Input Capacitance (V_{EB} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)		C _e	-	25	pF
SWITCHING TIMES $(T_A = 25^{\circ}C)$					
Delay Time (V _{CC} =	30 Vdc, $I_{C} = 150 \text{ mAdc}$,	t _d	-	10	ns
Rise Time I _{B(on)} = Figure	15 mAdc, V _{EB(off)} = 0.5 Vdc) 1	t _r	-	25	
Storage Time (V _{CC} =	30 Vdc, I _C = 150 mAdc,	ts	_	225	ns
(00	I _{B(off)} = 15 mAdc)	1	1	1	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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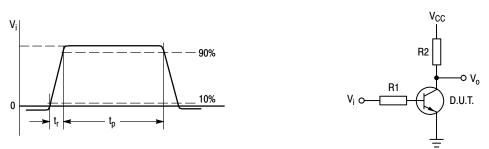
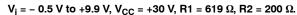


Figure 1. Input Waveform and Test Circuit for Determining Delay Time and Rise Time



PULSE GENERATOR:		OSCILLOSCOPE:	
PULSE DURATION RISE TIME	t _p 3 200 ns t _r 3 2 ns	INPUT IMPEDANCE	Z _i > 100 kΩ C _i < 12 pF
DUTY FACTOR	$\delta = 0.02$	RISE TIME	t _r < 5 ns

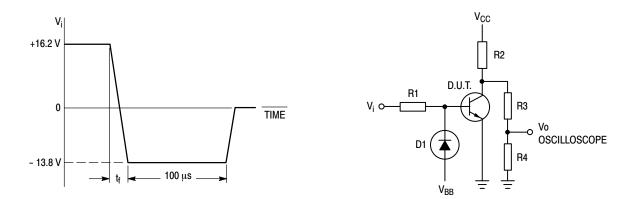
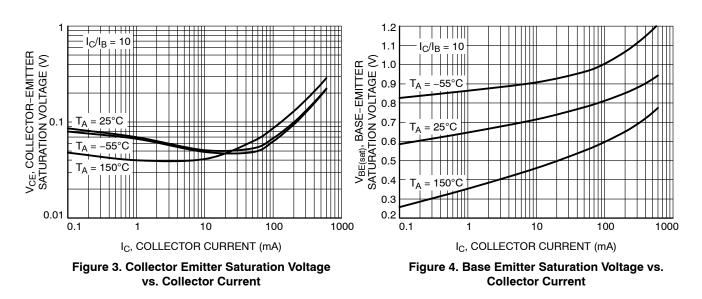


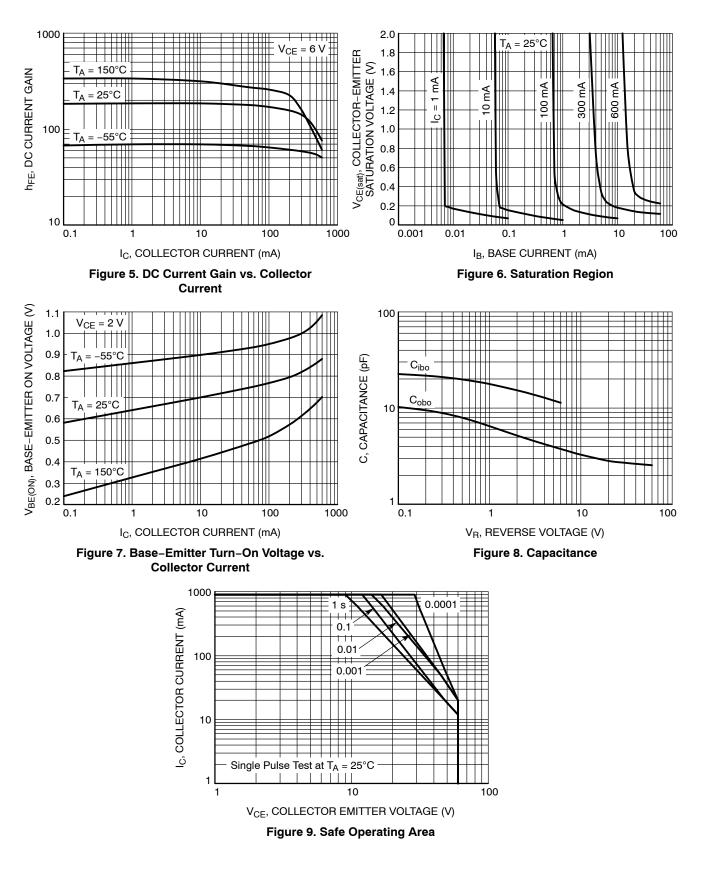
Figure 2. Input Waveform and Test Circuit for Determining Storage Time and Fall Time



TYPICAL CHARACTERISTICS

PZT2222A

TYPICAL CHARACTERISTICS



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SEE DETAIL A

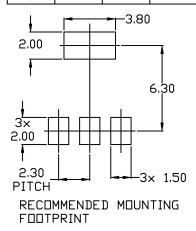
FRONT VIEW

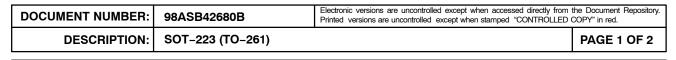
DATE 02 OCT 2018



- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- AI IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS & AND &1.

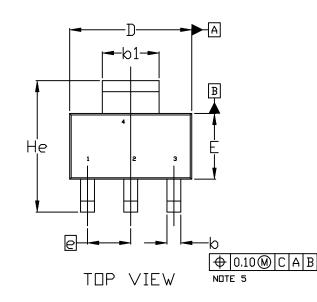
	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
с	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
e	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10 °	

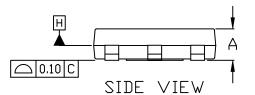


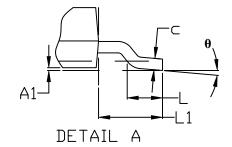


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SCALE 1:1







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STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	Style 4: Pin 1. Source 2. Drain 3. Gate 4. Drain	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: Pin 1. Input 2. Ground 3. Logic 4. Ground	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	Style 12: Pin 1. Input 2. Output 3. NC 4. Output	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package
- (Note: Microdot may be in either location) *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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